



## Material Composition Sheet

Product: GS7005-CQTE3  
 Package Type: MQFP-52 pin (84/tray)  
 Manufacturer: Gennum Corporation

Date: 11-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		14.20	Al	0.09	0.63	6338
			Si	14.11	99.36	993662
			Sub-total:	14.20	99.99	1000000
Die Attach	3230	3.30	Ag	2.51	76.06	760606
			Epoxy Resin	0.43	13.03	130303
			Epoxy Silane	0.04	1.21	12121
			Phenol Resin	0.09	2.72	27273
			t-Butylphenylglycidil ether	0.23	6.96	69697
			Sub-total:	3.30	99.98	1000000
Heat Sink		47.00	Al	47.00	100.00	1000000
			Sub-total:	47.00	100.00	1000000
Lead Finish External		11.50	Sn	11.50	100.00	1000000
			Sub-total:	11.50	100.00	1000000
Lead Finish Internal		0.90	Ag	0.90	100.00	1000000
			Sub-total:	0.90	100.00	1000000
Leadframe	OLIN 7025	196.20	Cu	188.74	96.19	961978
			Mg	0.29	0.14	1478
			Ni	5.89	3.00	30020
			Si	1.28	0.65	6524
			Sub-total:	196.20	99.98	1000000
Marking Ink		0.00		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G700M	675.30	Carbon Black	3.38	0.50	5005
			Epoxy Resin	54.02	7.99	79994
			Phenol Resin	43.89	6.49	64993
			SiO2	574.01	85.00	850007
Sub-total:	675.30	99.98	999999			
Wires		1.60	Au	1.60	100.00	1000000
			Sub-total:	1.60	100.00	1000000
<b>Total:</b>		<b>950.00</b>				

### GENNUM CORPORATION

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